

Marked up pages 1 and 3 and clean pages 1 and 3 are attached, pursuant to 37 CFR 1.121.

In the Claims:

Amend claims 1, 9 and 40 and 41 as follows.

1. (Amended) A surface-mounting substrate for mounting a part thereon, which comprises a core substrate, a plurality of layers of patterned wiring lines, which are separated from each other by an insulation layer interposed therebetween, vias piercing through the insulation layer to connect the wiring lines at the adjacent layers to each other, and a layer of connecting terminals to mount a part on the surface-mounting substrate, each of the connecting terminals connecting with the wiring line at the outermost layer of wiring lines, wherein the connecting terminal is filled in an outermost insulation layer provided at the surface of the surface-mounting substrate, and has a surface exposed at substantially the same level as the level of the surface of the outermost insulation layer, the connecting terminal being provided on its surface with solder material.
9. (Amended) The surface-mounting substrate of claim 1, wherein the connecting terminals are arranged at a pitch of 100 micrometers or smaller and at a [spacing] distance between the terminals of 200 micrometers or larger.
40. (Amended) A structure comprising a surface-mounting substrate and a part mounted thereon, the surface-mounting substrate comprising a core substrate, a plurality of layers of patterned wiring lines, which are separated from each other by an insulation layer interposed therebetween, vias piercing through the insulation layer to connect the wiring lines at the adjacent layers to each other, and a layer of connecting terminals to mount the part on the surface-mounting substrate, each of connecting terminals connecting with the wire line at the outermost layer of wiring lines, and the part having bumps, and being mounted on the substrate

through the bumps bonded to the respective connecting terminals, wherein the connecting terminal of the surface-mounting substrate is filled in an outermost insulation layer provided at the surface of the surface-mounting substrate such that the entire surface of a connecting terminal is exposed at the surface of the mounting substrate, and has a surface exposed at substantially the same level as the level of the surface of the outermost insulation layer, the connecting terminal being provided on its surface with solder material.

41. (Amended) the structure of claim 40, wherein the part to be mounted is a semiconductor device and wherein at least one of said layers of patterned wiring lines is a dummy layer.

Delete claims ~~2,3~~ and add new claims 53-54, as follows.

53. The surface-mounting substrate of claim 1, wherein the wiring lines of the respective wiring line layers below the connecting terminals are arranged at the same density as the density of connecting terminals so as to be each located under a respective connecting terminal.

54. The surface-mounting substrate of claim 40, wherein the wiring lines of the respective wiring line layers below the connecting terminals are arranged at the same density as the density of connecting terminals so as to be each located under a respective connecting terminal.

Clean copies of these claims are attached below, pursuant to 37 CFR 1.121.